IEC 60749-22-1

Edition 1.0 2025-11

INTERNATIONAL STANDARD

Semiconductor devices - Mechanical and climatic test methods - Part 22-1: Bond strength - wire bond pull test methods

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ICS 31.080.01

ISBN 978-2-8327-0861-3

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IEC 60749-22-1 has been prepared by IEC technical committee 47: Semiconductor devices. It is an International Standard.

This International Standard is to be used in conjunction with IEC 60749-22-2:2025.

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This edition includes the following significant technical changes with respect to the previous edition:

a) Major update, including new techniques and use of new materials (e.g. copper wire) involving a complete rewrite as two separate subparts (this document and IEC 60749-22-2).